A method of and apparatus for aligning the bonding head of a bonder or a pick and place machine

ABSTRACT OF THE DISCLOSURE

A method of aligning the bonding head (3) of a bonder, in particular of a die bonder (1), or of a pick and place machine which comprises the following steps:

a) placement of an alignment plate (10) provided with two plane parallel surfaces (8, 9) on a supporting surface (6) which is set plane parallel to the bonding surface (2), upon which the semiconductor chip will be bonded to the carrier material;

b) calibration of a measuring device (7) the signal of which is dependent upon the position of the alignment plate (10);

c) grasping the alignment plate (10) with the bonding head (3) of the bonder and holding the alignment plate (10) free at a slight distance above the measuring device (7);

d) alignment of the bonding head (3), until the signal from the measuring device (7) is equal to the signal following step b).

Apparatuses suitable for implementing the method are also disclosed.

(Fig. 1)